

TE Internal #: 2501552-7

RJ45 Connector, Multiple Ports, 2 x 1, Standard Connector Contact

Density, Jack, Shielded, Cat 5, Inverted (Top) / Standard (Bottom), 8

Position

View on TE.com >



Connectors > Modular Jacks & Plugs > RJ45 Connectors > Industrial RJ45 modular jacks: 10/100 Mbps and 1 Gbps, THT reflow solderable











Modular Jack & Plug Interface Type: RJ45

Port Configuration: Multiple Ports

Port Matrix Configuration: 2 x 1

Modular Jacks & Plugs Products: RJ Type Jacks & Plugs

Connector Contact Density: Standard

All Industrial RJ45 modular jacks: 10/100 Mbps and 1 Gbps, THT reflow solderable (36)

## Features

## **Product Type Features**

Connector Product Type	Connector Assembly
Modular Jack & Plug Interface Type	RJ45
Modular Jacks & Plugs Products	RJ Type Jacks & Plugs
Modular Connector Style	Jack
Grounding Options	PCB Ground
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of PCB Ground Tabs	4
Number of Panel Ground Tabs	0
Multiple Port Configuration	Stacked
Port Configuration	Multiple Ports
Port Matrix Configuration	2 x 1
Connector Contact Density	Standard



Number of Positions	8
Number of Loaded Positions	8
PCB Mount Orientation	Right Angle
Signal Characteristics	
Data Rate	10 Mb/s, 100 Mb/s
Body Features	
LED Color (Top Left)	None
PCB Retention Feature Material	LCP
LED Color (Bottom Left)	None
LED Color (Top Right)	None
Insulator Material	LCP
LED Color (Bottom Right)	None
Shield Plating Material	Nickel
Shield Material	Copper Alloy
Modular Jack Latch Orientation	Inverted (Top) / Standard (Bottom)
Connector Profile	Standard
Contact Features	
PCB Contact Termination Area Plating Material Finish	Matte
PCB Contact Termination Area Plating Material Finish  Contact Underplating Material	Matte Nickel
Contact Underplating Material	Nickel
Contact Underplating Material  PCB Contact Termination Area Plating Material	Nickel
Contact Underplating Material  PCB Contact Termination Area Plating Material  Contact Current Rating (Max)	Nickel Tin 1.5 A
Contact Underplating Material  PCB Contact Termination Area Plating Material  Contact Current Rating (Max)  Contact Mating Area Plating Material	Nickel Tin 1.5 A Gold
Contact Underplating Material  PCB Contact Termination Area Plating Material  Contact Current Rating (Max)  Contact Mating Area Plating Material  Contact Base Material	Nickel Tin 1.5 A Gold Phosphor Bronze
Contact Underplating Material  PCB Contact Termination Area Plating Material  Contact Current Rating (Max)  Contact Mating Area Plating Material  Contact Base Material  Contact Mating Area Plating Material Thickness	Nickel Tin 1.5 A Gold Phosphor Bronze
Contact Underplating Material  PCB Contact Termination Area Plating Material  Contact Current Rating (Max)  Contact Mating Area Plating Material  Contact Base Material  Contact Mating Area Plating Material Thickness  Termination Features	Nickel Tin 1.5 A Gold Phosphor Bronze .76 µm[30 µin]
Contact Underplating Material  PCB Contact Termination Area Plating Material  Contact Current Rating (Max)  Contact Mating Area Plating Material  Contact Base Material  Contact Mating Area Plating Material Thickness  Termination Features  Termination Method to PCB	Nickel  Tin  1.5 A  Gold  Phosphor Bronze  .76 µm[30 µin]  Through Hole - Solder
Contact Underplating Material  PCB Contact Termination Area Plating Material  Contact Current Rating (Max)  Contact Mating Area Plating Material  Contact Base Material  Contact Mating Area Plating Material Thickness  Termination Features  Termination Method to PCB  Termination Post & Tail Length	Nickel  Tin  1.5 A  Gold  Phosphor Bronze  .76 µm[30 µin]  Through Hole - Solder
Contact Underplating Material  PCB Contact Termination Area Plating Material  Contact Current Rating (Max)  Contact Mating Area Plating Material  Contact Base Material  Contact Mating Area Plating Material Thickness  Termination Features  Termination Method to PCB  Termination Post & Tail Length  Mechanical Attachment	Nickel  Tin  1.5 A  Gold  Phosphor Bronze  .76 µm[30 µin]  Through Hole - Solder  2.54 mm[.1 in]
Contact Underplating Material  PCB Contact Termination Area Plating Material  Contact Current Rating (Max)  Contact Mating Area Plating Material  Contact Base Material  Contact Mating Area Plating Material Thickness  Termination Features  Termination Method to PCB  Termination Post & Tail Length  Mechanical Attachment  PCB Mount Retention Type	Nickel  Tin  1.5 A  Gold  Phosphor Bronze  .76 µm[30 µin]  Through Hole - Solder  2.54 mm[.1 in]
Contact Underplating Material  PCB Contact Termination Area Plating Material  Contact Current Rating (Max)  Contact Mating Area Plating Material  Contact Base Material  Contact Mating Area Plating Material Thickness  Termination Features  Termination Method to PCB  Termination Post & Tail Length  Mechanical Attachment  PCB Mount Retention Type  Connector Mounting Type	Nickel  Tin  1.5 A  Gold  Phosphor Bronze  .76 µm[30 µin]  Through Hole - Solder  2.54 mm[.1 in]



Housing Color	Black
Housing Material	LCP (Liquid Crystal Polymer)
Dimensions	
Connector Height	25.4 mm[1 in]
Usage Conditions	
Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]
Operation/Application	
Shielded	Yes
Industry Standards	
UL Flammability Rating	UL 94V-0
Performance Category	Cat 5
Packaging Features	
Packaging Method	Tray

## **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Not Yet Reviewed
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Not reviewed for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished



product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

# Compatible Parts









### **Documents**

**Product Drawings** 

RJ45 JACK THR 10/100 R/A 2X1

English

**CAD Files** 

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_2501552-7\_1.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2501552-7\_1.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2501552-7\_1.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

**Product Specifications** 

**Application Specification** 

English